

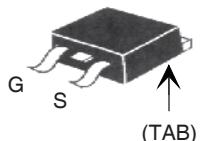
Trench Gate Power MOSFET

**IXTA50N25T IXTH50N25T
IXTP50N25T IXTQ50N25T**

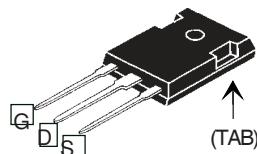
N-Channel Enhancement Mode

 $V_{DSS} = 250V$
 $I_{D25} = 50A$
 $R_{DS(on)} \leq 50m\Omega$

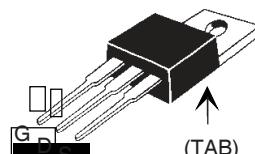
TO-263 (IXTA)



TO-247 (IXTH)

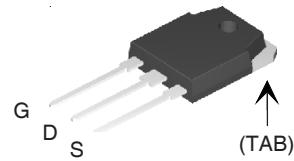


TO-220 (IXTP)



Symbol	Test Conditions	Maximum Ratings		
V_{DSS}	$T_J = 25^\circ C$ to $150^\circ C$	250		V
V_{DGR}	$T_J = 25^\circ C$ to $150^\circ C$, $R_{GS} = 1M\Omega$	250		V
V_{GSM}	Transient	± 30		V
I_{D25}	$T_c = 25^\circ C$	50		A
I_{DM}	$T_c = 25^\circ C$, pulse width limited by T_{JM}	130		A
I_{AS}	$T_c = 25^\circ C$	5		A
E_{AS}	$T_c = 25^\circ C$	1.5		J
P_D	$T_c = 25^\circ C$	400		W
T_J		-55 ... +150		$^\circ C$
T_{JM}		150		$^\circ C$
T_{stg}		-55 ... +150		$^\circ C$
T_L	1.6mm (0.062in.) from case for 10s Plastic body for 10 seconds	300 260		$^\circ C$
M_d	Mounting Torque TO-220,TO-3P,TO247	1.13 / 10		Nmlb.in.
F_c	Mounting Force TO-263	10..65 / 2.2..14.6		N/lb.
Weight	TO-263 TO-220 TO-3P TO-247	2.5 3.0 5.5 6.0		g

TO-3P (IXTQ)


 G = Gate
 S = Source

 D = Drain
 TAB = Drain
Features

- International standard packages
- Avalanche rated
- Low package inductance
 - easy to drive and to protect

Advantages

- Easy to mount
- Space savings
- High power density

Symbol	Test Conditions ($T_J = 25^\circ C$ unless otherwise specified)	Characteristic Values		
		Min.	Typ .	Max.
BV_{DSS}	$V_{GS} = 0V$, $I_D = 1mA$	250		V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 1mA$	3		V
I_{GSS}	$V_{GS} = \pm 20V$, $V_{DS} = 0V$		± 100 nA	
I_{DSS}	$V_{DS} = V_{DSS}$ $V_{GS} = 0V$		1 μA	
		$T_J = 125^\circ C$	150 μA	
$R_{DS(on)}$	$V_{GS} = 10V$, $I_D = 0.5 \cdot I_{D25}$, Note 1		50 m Ω	

Applications

- DC-DC converters
- Battery chargers
- Switched-mode and resonant-mode power supplies
- DC choppers
- AC motor control
- Uninterruptible power supplies
- High speed power switching applications

Symbol	Test Conditions ($T_J = 25^\circ\text{C}$ unless otherwise specified)	Characteristic Values		
		Min.	Typ.	Max.
g_{fs}	$V_{DS} = 10\text{V}$, $I_D = 0.5 \cdot I_{D25}$, Note 1	35	58	S
C_{iss}	$V_{GS} = 0\text{V}$, $V_{DS} = 25\text{V}$, $f = 1\text{MHz}$	4000	pF	
C_{oss}		410		
C_{rss}		60		pF
$t_{d(on)}$	Resistive Switching Times $V_{GS} = 15\text{V}$, $V_{DS} = 0.5 \cdot V_{DSS}$, $I_D = 0.5 \cdot I_{D25}$ $R_G = 3.3\Omega$ (External)	14	ns	
t_r		25		
$t_{d(off)}$		47		
t_f		25		ns
$Q_{g(on)}$	$V_{GS} = 10\text{V}$, $V_{DS} = 0.5 \cdot V_{DSS}$, $I_D = 0.5 \cdot I_{D25}$	78	nC	
Q_{gs}		19		nC
Q_{gd}		22		nC
R_{thJC}	TO-220	0.50	0.31	$^\circ\text{C}/\text{W}$
R_{thCH}				$^\circ\text{C}/\text{W}$
	TO-3P, TO-247	0.25		$^\circ\text{C}/\text{W}$

Source-Drain Diode

Symbol	Test Conditions ($T_J = 25^\circ\text{C}$ unless otherwise specified)	Characteristic Values		
		Min.	Typ.	Max.
I_s	$V_{GS} = 0\text{V}$		50	A
I_{SM}	Repetitive, pulse width limited by T_{JM}		200	A
V_{SD}	$I_F = I_S$, $V_{GS} = 0\text{V}$, Note 1		1.5	V
t_{rr}	$I_F = 25\text{A}$, $-di/dt = 250\text{A}/\mu\text{s}$ $V_R = 100\text{V}$, $V_{GS} = 0\text{V}$	166	ns	
I_{RM}		23		A
Q_{RM}		1.9		μC

Notes: 1: Pulse test, $t \leq 300\mu\text{s}$; duty cycle, $d \leq 2\%$.

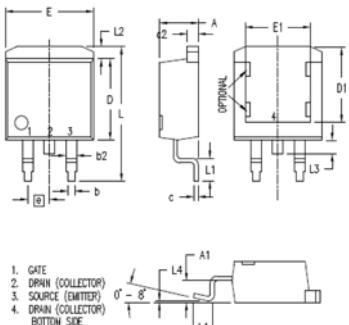
PRELIMINARY TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from data gathered during objective characterizations of preliminary engineering lots; but also may yet contain some information supplied during a pre-production design evaluation. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

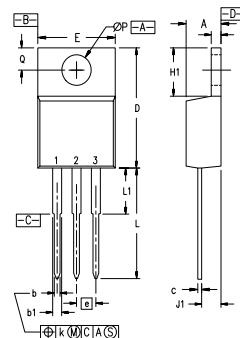
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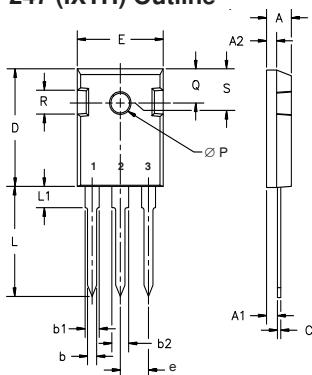
IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents:

4,835,592	4,931,844	5,049,961	5,237,481	6,162,665	6,404,065 B1	6,683,344	6,727,585	7,005,734 B2	7,157,338 B2
4,850,072	5,017,508	5,063,307	5,381,025	6,259,123 B1	6,534,343	6,710,405 B2	6,759,692	7,063,975 B2	
4,881,106	5,034,796	5,187,117	5,486,715	6,306,728 B1	6,583,505	6,710,463	6,771,478 B2	7,071,537	

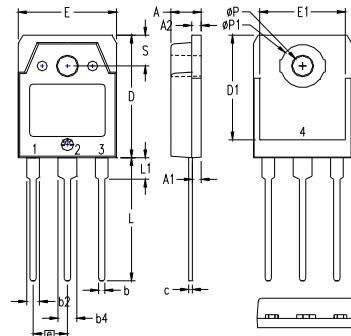
TO-263 (IXTA) Outline


SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.160	.190	4.06	4.83
A1	.080	.110	2.03	2.79
b	.020	.039	0.51	0.99
b2	.045	.055	1.14	1.40
c	.016	.029	0.40	0.74
c2	.045	.055	1.14	1.40
D	.340	.380	8.64	9.65
D1	.315	.350	8.00	8.89
E	.380	.410	9.65	10.41
E1	.245	.320	6.22	8.13
e	.100 BSC		2.54 BSC	
L	.575	.625	14.61	15.88
L1	.090	.110	2.29	2.79
L2	.040	.055	1.02	1.40
L3	.050	.070	1.27	1.78
L4	0	.005	0	0.13

TO-220 (IXTP) Outline

 Pins: 1 - Gate 2 - Drain
 3 - Source 4 - Drain

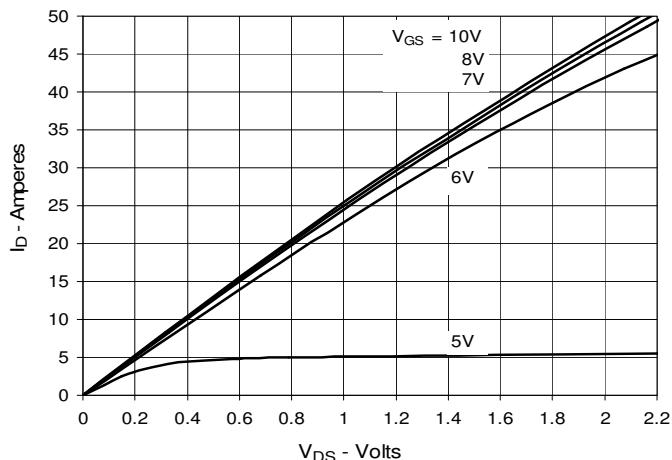
TO-247 (IXTH) Outline

 Terminals: 1 - Gate 2 - Drain
 3 - Source Tab - Drain

Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	4.7	5.3	.185	.209
A ₁	2.2	2.54	.087	.102
A ₂	2.2	2.6	.059	.098
b	1.0	1.4	.040	.055
b ₁	1.65	2.13	.065	.084
b ₂	2.87	3.12	.113	.123
C	.4	.8	.016	.031
D	20.80	21.46	.819	.845
E	15.75	16.26	.610	.640
e	5.20	5.72	0.205	0.225
L	19.81	20.32	.780	.800
L1		4.50		.177
ØP	3.55	3.65	.140	.144
Q	5.89	6.40	0.232	0.252
R	4.32	5.49	.170	.216
S	6.15	BSC		242 BSC

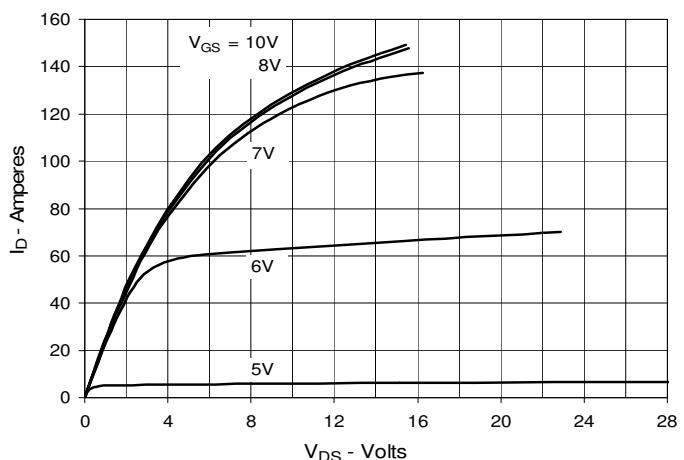
TO-3P (IXTQ) Outline

 1 - GATE
 2 - DRAIN (COLLECTOR)
 3 - SOURCE (EMITTER)
 4 - DRAIN (COLLECTOR)

SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.185	.193	4.70	4.90
A1	.051	.059	1.30	1.50
A2	.057	.065	1.45	1.65
b	.035	.045	0.90	1.15
b2	.075	.087	1.90	2.20
b4	.114	.126	2.90	3.20
c	.022	.031	0.55	0.80
D	.780	.799	19.80	20.30
D1	.665	.677	16.90	17.20
E	.610	.622	15.50	15.80
E1	.531	.539	13.50	13.70
e		215 BSC		5.45 BSC
L	.779	.795	19.80	20.20
L1	.134	.142	3.40	3.60
ØP	.126	.134	3.20	3.40
ØP1	.272	.280	6.90	7.10
S	.193	.201	4.90	5.10

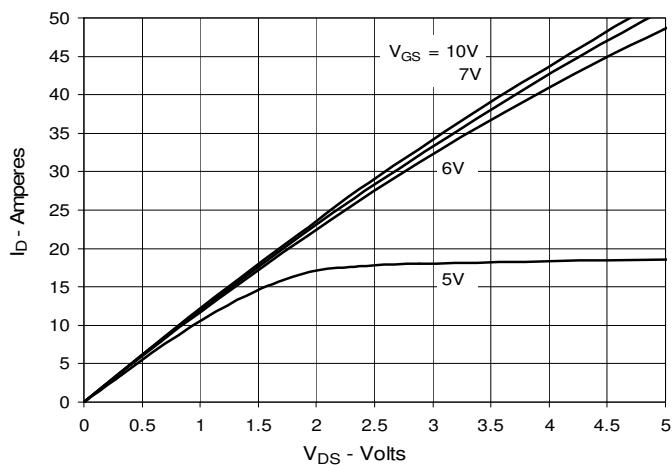
**Fig. 1. Output Characteristics
@ 25°C**



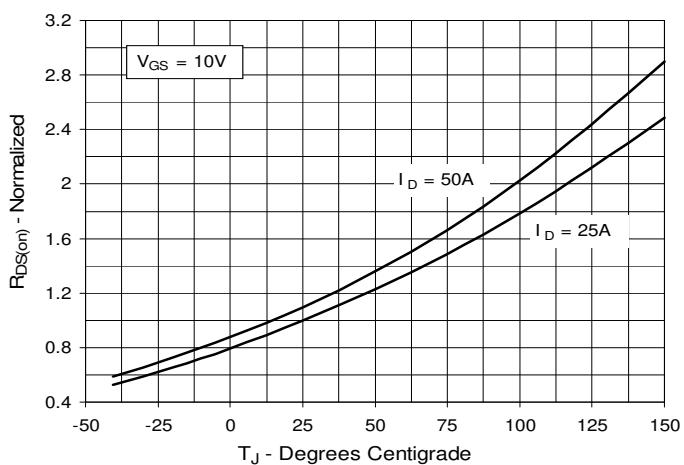
**Fig. 2. Extended Output Characteristics
@ 25°C**



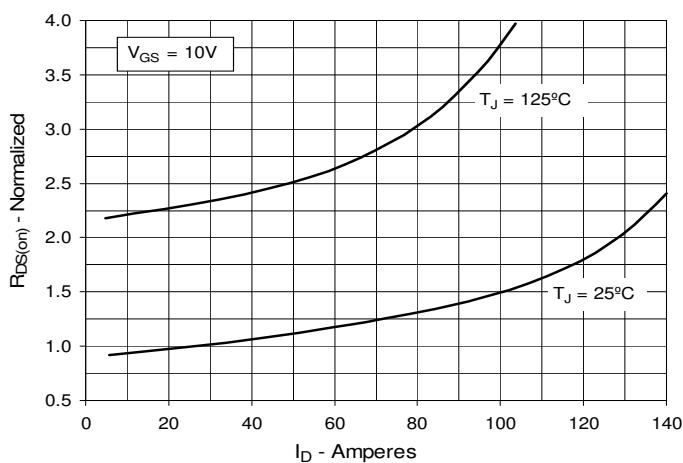
**Fig. 3. Output Characteristics
@ 125°C**



**Fig. 4. $R_{DS(on)}$ Normalized to $I_D = 25A$ Value
vs. Junction Temperature**



**Fig. 5. $R_{DS(on)}$ Normalized to $I_D = 25A$ Value
vs. Drain Current**



**Fig. 6. Maximum Drain Current vs.
Case Temperature**

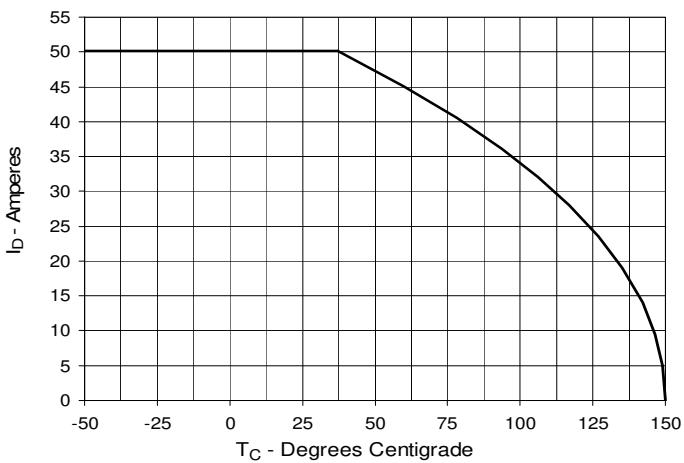
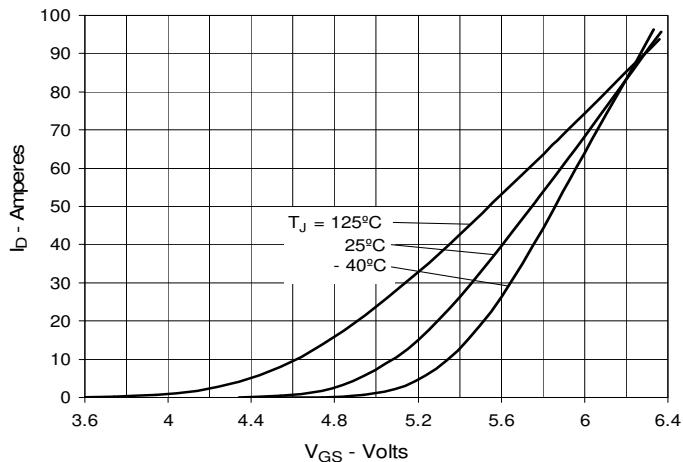
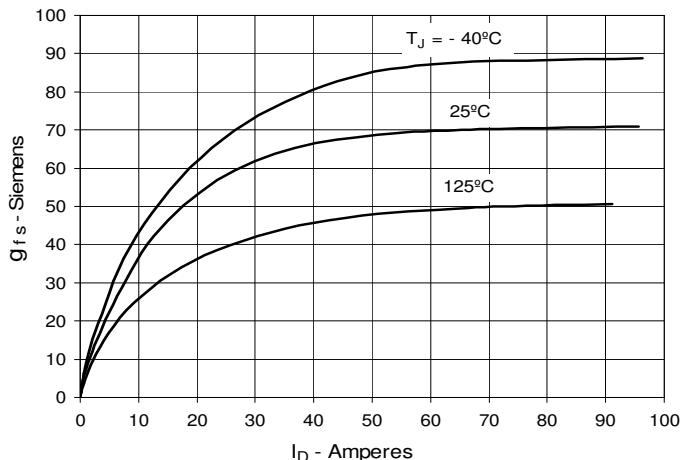
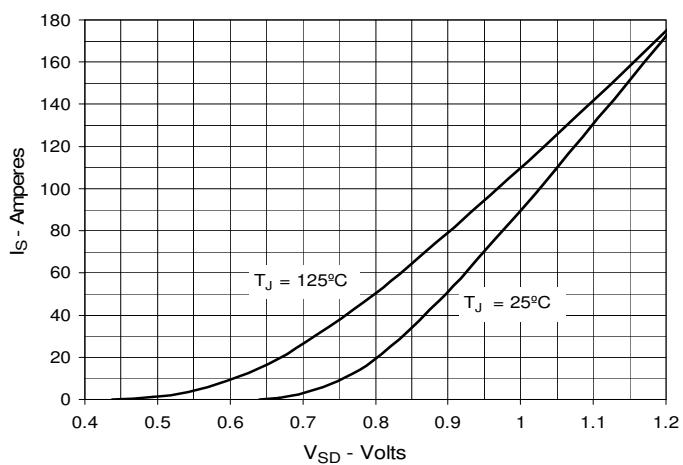
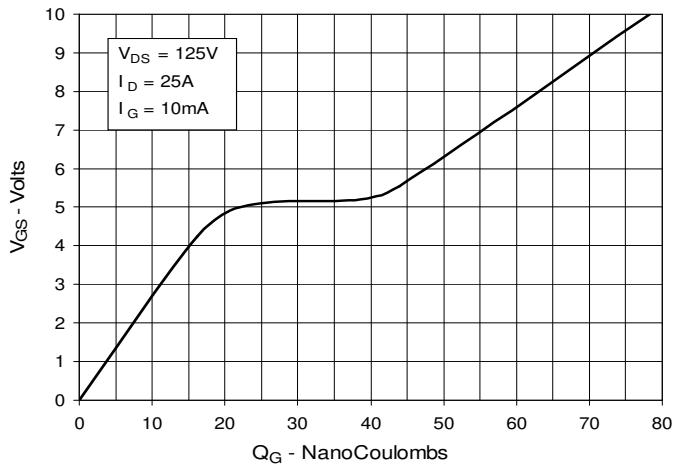
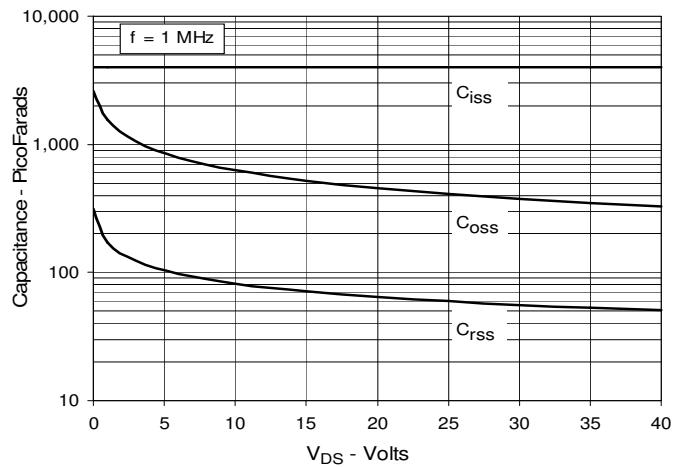
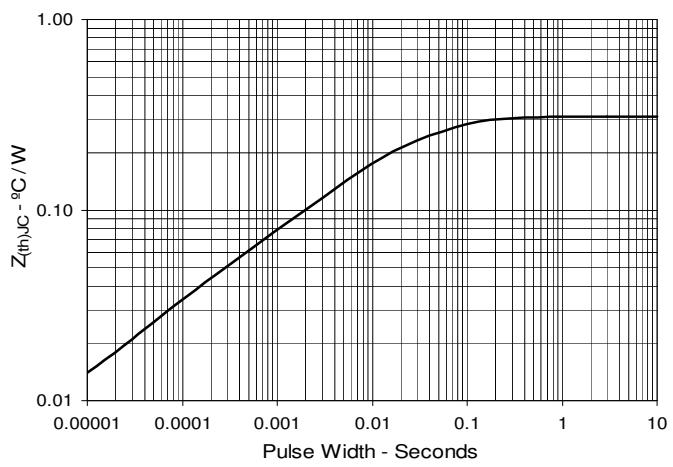
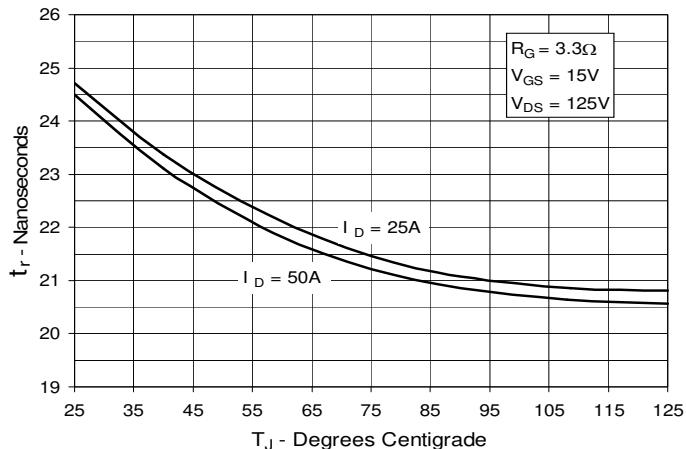
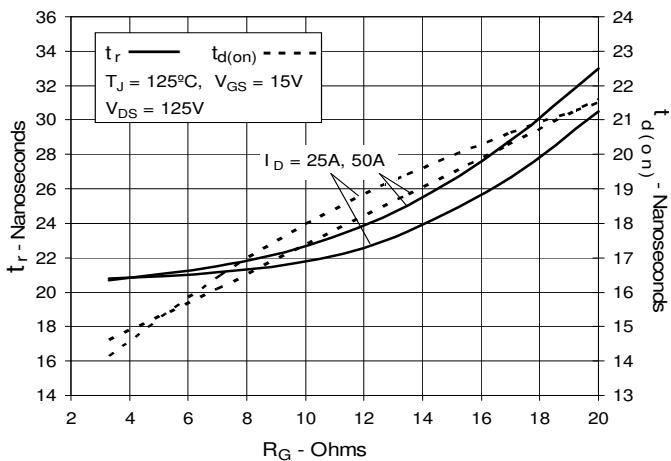


Fig. 7. Input Admittance

Fig. 8. Transconductance

Fig. 9. Forward Voltage Drop of Intrinsic Diode

Fig. 10. Gate Charge

Fig. 11. Capacitance

Fig. 12. Maximum Transient Thermal Impedance


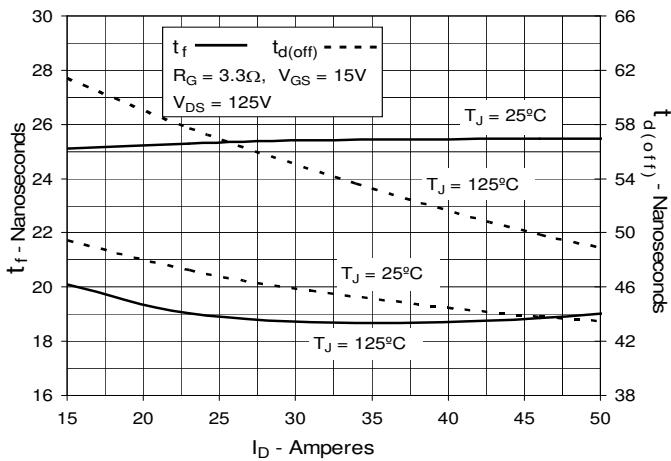
**Fig. 13. Resistive Turn-on
Rise Time vs. Junction Temperature**



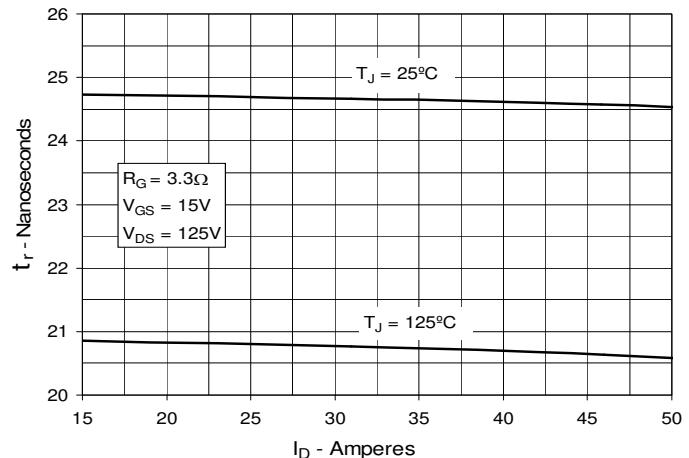
**Fig. 15. Resistive Turn-on
Switching Times vs. Gate Resistance**



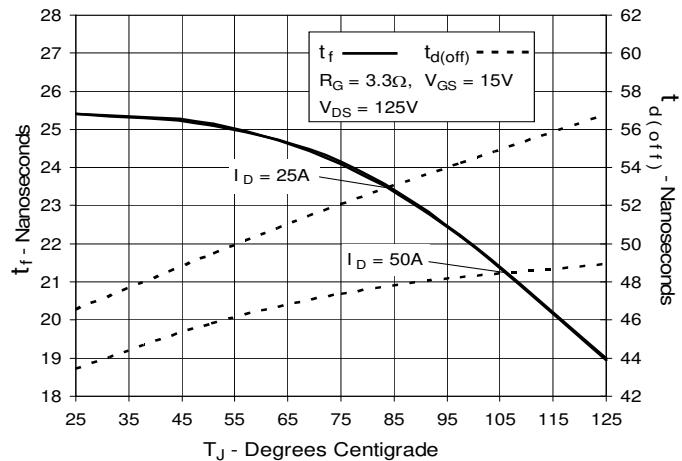
**Fig. 17. Resistive Turn-off
Switching Times vs. Drain Current**



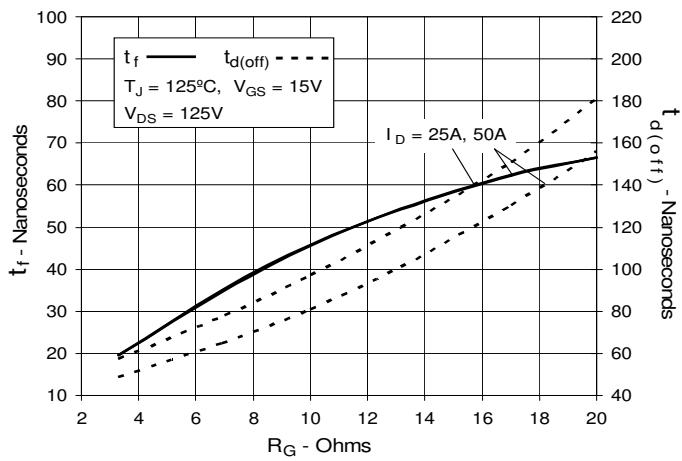
**Fig. 14. Resistive Turn-on
Rise Time vs. Drain Current**



**Fig. 16. Resistive Turn-off
Switching Times vs. Junction Temperature**



**Fig. 18. Resistive Turn-off
Switching Times vs. Gate Resistance**



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